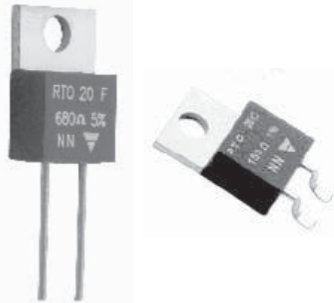


## 20 W Power Resistor, Thick Film Technology, TO-220



The well known TO-220 package is compact and easy to mount.

### FEATURES

- 20 W at 25 °C heatsink mounted
- High power dissipation to size ratio
- Wide resistance range from 0.01 Ω to 550 kΩ
- Negligible inductance
- Easy mounting
- TO-220 package: Compact and easy to mount
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

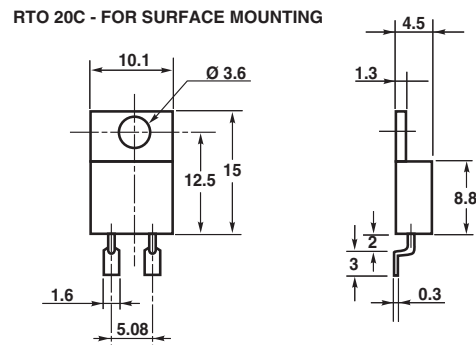
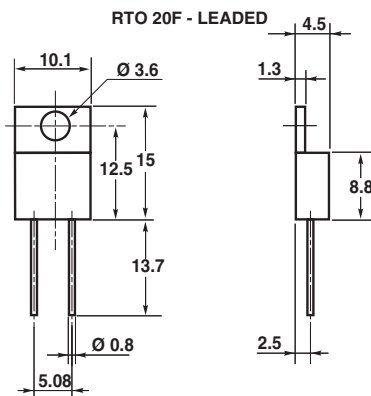


**RoHS**  
COMPLIANT

Two versions of this thick film resistor are available:

- A radial leaded version for PCB mounting
- A flat lead version for surface mounting

### DIMENSIONS in millimeters



• Only for RTO 20 version C = during surface mount soldering temperature profile must not cause the metal tab of this device to exceed 220 °C.

#### Note

- Tolerances unless stated: ± 0.4 mm

### STANDARD ELECTRICAL SPECIFICATIONS

MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER $P_{25^{\circ}\text{C}}$ W	LIMITING ELEMENT VOLTAGE $U_L$ V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C	CRITICAL RESISTANCE Ω
RTO 20	TO-220	0.010 to 550K <sup>(1)</sup>	20	500	1, 2, 5, 10	150	12.5K

#### Note

<sup>(1)</sup> E24 series

### MECHANICAL SPECIFICATIONS

Mechanical Protection	Insulated case
Resistive Element	Thick film
Substrate	Alumina onto base of nickel coated copper
Connections	Tinned copper
Weight	2.2 g max.

### ENVIRONMENTAL SPECIFICATIONS

Temperature Range	-55 °C to 155 °C
Climatic Category	55/155/56
Sealing	Sealed container, solder immersion
Flammability	IEC 60695-11-5 2 applications 30 s separated by 60 s

### TECHNICAL SPECIFICATIONS

Dissipation and Associated	Onto a heatsink
Thermal Resistance and Nominal Power	20 W at +25 °C $R_{\text{TH}(j-c)}$ : 6.5 °C/W Free air: 2 W at +25 °C
Dielectric Strength MIL STD 202	2000 $V_{\text{RMS}}$ - 1 min - 10 mA max. (between terminals and heatsink)
Insulation Resistance	≥ 10 <sup>6</sup> MΩ
Inductance	≤ 0.1 μH

### DIMENSIONS

Standard Package	TO-220 insulated case
------------------	-----------------------

#### Note

- Not compatible with RoHS reflow profile.



PERFORMANCE		
TESTS	CONDITIONS	REQUIREMENTS
Momentary Overload	EN 60115-1 2 Pr 5 s for $R < 2 \Omega$ 1.6 Pr 5 s for $R \geq 2 \Omega$ $U_S < 1.5 U_L$	$\pm (0.25 \% + 0.005 \Omega)$
Rapid Temperature Change	EN 60115-1/60068-2-14 5 cycles -55 °C to +155 °C	$\pm (0.5 \% + 0.005 \Omega)$
Load Life	EN 60115-1 1000 h Pr at +25 °C	$\pm (1 \% + 0.005 \Omega)$
Humidity (Steady State)	EN 60115-1 56 days RH 95 %	$\pm (0.5 \% + 0.005 \Omega)$
High Temperature Exposure	NF EN 140 000 1000 h - 40 % Pr at +100 °C	$\pm (0.5 \% + 0.005 \Omega)$
Vibration	MIL STD 202, Method 204 C Test D	$\pm (0.2 \% + 0.005 \Omega)$
Terminal Strength	MIL STD 202, Method 211 Test A1	$\pm (0.2 \% + 0.005 \Omega)$
Shock	IEC 60115-1 IEC 60068-2-27 Saw tooth: 100 g/6 ms	$\pm (0.5 \% + 0.005 \Omega)$

RESISTANCE VALUE IN RELATION TO TOLERANCE AND TCR				
Resistance Values	$\geq 0.01$	$\geq 0.015$	$\geq 0.1$	$\geq 0.5$
Tolerances	$\pm 1 \%$ at $\pm 10 \%$			
Typical Temperature Coefficient Range (-55 °C to +155 °C)	$\pm 900$ ppm/°C	$\pm 700$ ppm/°C	$\pm 250$ ppm/°C	$\pm 150$ ppm/°C

**Note**

- For very low ohmic values, TCR for information.

**CHOICE OF THE HEATSINK**

The user must choose the board according to the working conditions of the component (power, room temperature). Maximum working temperature must not exceed 155 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{R_{TH(j-c)} + R_{TH(c-h)} + R_{TH(h-a)}} \quad (1)$$

P: Expressed in W

$\Delta T$ : Difference between maximum working temperature and room temperature

$R_{TH(j-c)}$ : Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal resistance of the component: Special Features table.

$R_{TH(c-h)}$ : Thermal resistance value measured between outer side of the resistor and upper side of the heatsink. This is the thermal resistance of the interface (grease, thermal pad), and the quality of the fastening device.

$R_{th(h-a)}$ : Thermal resistance of the heatsink.

**Example:**

$R_{TH(c-a)}$  for RTO 20 power rating 10 W at ambient temperature +25 °C

Thermal resistance  $R_{TH(j-c)}$ : 6.5 °C/W

Considering equation (1) we have:

$$\Delta T = 155 \text{ °C} - 25 \text{ °C} = 130 \text{ °C}$$

$$R_{TH(j-c)} + R_{TH(c-h)} + R_{TH(h-a)} = \frac{\Delta T}{P} = \frac{130}{10} = 13 \text{ °C/W}$$

$$R_{TH(c-h)} + R_{TH(h-a)} = 13 \text{ °C/W} - 6.5 \text{ °C/W} = 6.5 \text{ °C/W}$$



**OVERLOADS**

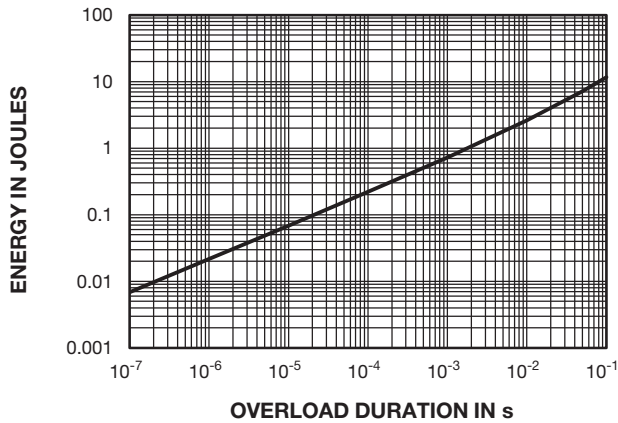
In any case the applied voltage must be lower than the maximum overload voltage of 750 V.

The values indicated on the graph below are applicable to resistors in air or mounted onto a heatsink.

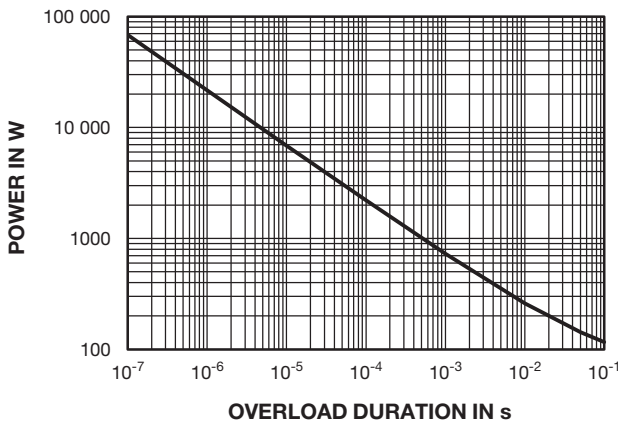
**MARKING**

Model, style, resistance value (in Ω), tolerance (in %), manufacturing date, Vishay Sfernice trademark.

**ENERGY CURVE**



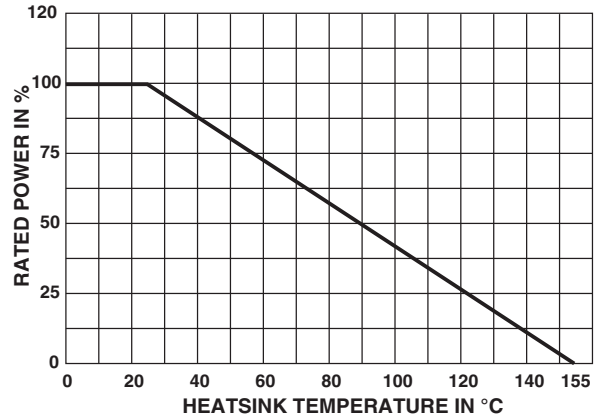
**POWER CURVE**



**POWER RATING**

The temperature of the heatsink should be maintained within the limits specified.

To improve the thermal conductivity, surfaces in contact should be coated with a silicone grease and the torque applied on the screw for tightening should be around 1 Nm. Spring clip can also be used to mount the component on an heatsink (ex: Kunze, clip KU4-498).

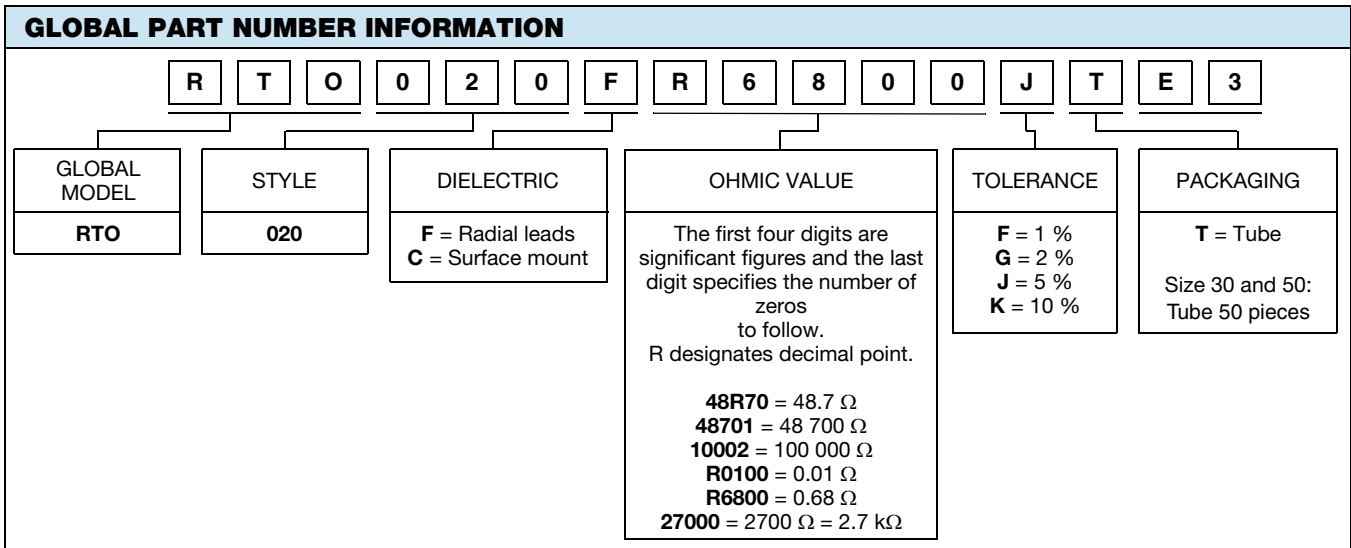


**PACKAGING**

Tube of 50 units



ORDERING INFORMATION							
<b>RTO</b>	<b>20</b>	<b>F</b>	<b>U68</b>	<b>5 %</b>	<b>xxx</b>	<b>TU50</b>	<b>e3</b>
MODEL	STYLE	CONNECTIONS	RESISTANCE VALUE	TOLERANCE	CUSTOM DESIGN	PACKAGING	LEAD (Pb)-FREE
		<b>F:</b> Radial leads <b>C:</b> Surface mount		± 1 % ± 2 % ± 5 % ± 10 %	Optional on request: Special TCR, shape etc.		





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